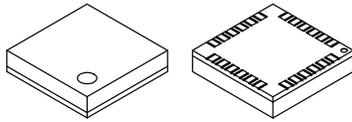


# MECHANICAL CASE OUTLINE

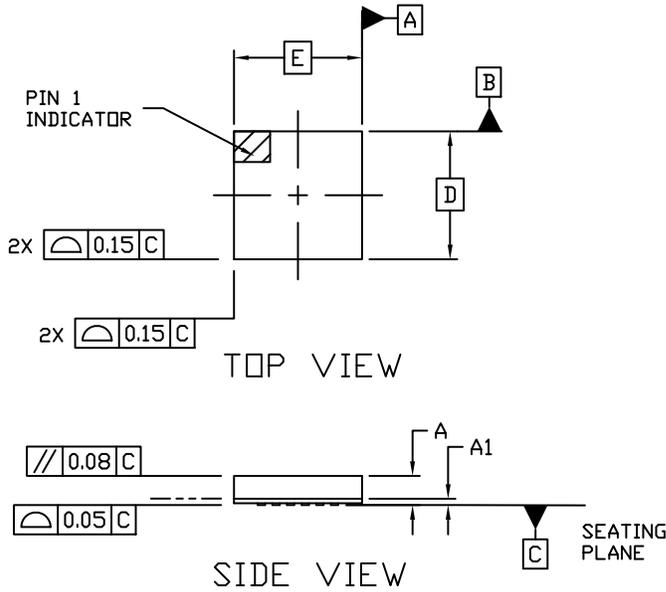
## PACKAGE DIMENSIONS

ON Semiconductor®



VQLP24 3.5x3.5, 0.4P  
CASE 602AA  
ISSUE A

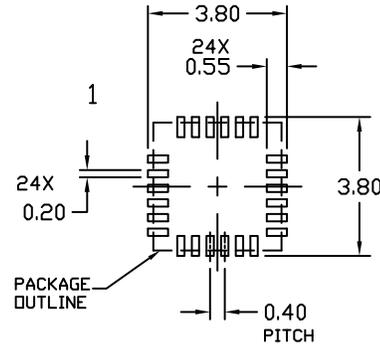
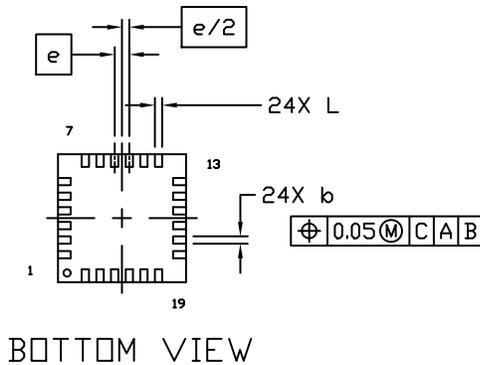
DATE 29 JAN 2014



NOTES:

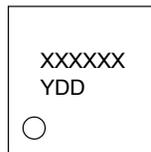
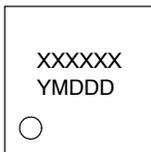
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS

DIM	MILLIMETERS	
	MIN.	MAX.
A	---	0.85
A1	---	0.05
b	0.15	0.25
D	3.50 BSC	
E	3.50 BSC	
e	0.40 BSC	
L	0.30	0.40



RECOMMENDED MOUNTING FOOTPRINT

GENERIC MARKING DIAGRAM\*



XXXXXX = Specific Device Code  
Y = Year  
M = Month  
DDD = Additional Traceability Data

XXXXXX = Specific Device Code  
Y = Year  
DD = Additional Traceability Data

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>VQLP24 3.5X3.5, 0.4P</b>	<b>PAGE 1 OF 2</b>

